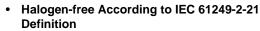


2SJ531-VB Datasheet P-Channel 60 V (D-S) MOSFET

PRODUCT	SUMMARY		
V _{DS} (V)	$R_{DS(on)}(\Omega)$ Max.	I _D (A)	Q _g (Typ.)
- 60	$0.050 \text{ at V}_{GS} = -10 \text{ V}$	- 30	67
	0.060 at $V_{GS} = -4.5 \text{ V}$	- 24	07

FEATURES

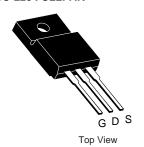


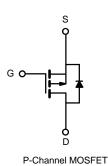


- Trench Power MOSFET
- 100 % R_g and UIS Tested
- Compliant to RoHS Directive 2002/95/EC



TO-220 FULLPAK





ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)							
Parameter		Symbol	Limit	Unit			
Drain-Source Voltage		V _{DS}	- 60	V			
Gate-Source Voltage	V _{GS}	± 20	7 v				
Continuous Drain Current (T _{.I} = 150 °C)	T _C = 25 °C	1_	- 30				
Committees Drain Current (1) = 100 C)	T _C = 70 °C	l _D	- 29	A			
Pulsed Drain Current (t = 300 μs)	I _{DM}	- 100					
Avalanche Current	I _{AS}	- 32					
Single Avalanche Energy ^a	L = 0.1 mH	E _{AS}	51	mJ			
Maximum Power Dissipation ^a	T _C = 25 °C	В	41.7 ^b	144			
	T _A = 25 °C ^c	$ P_D$	2.1	W			
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C			

THERMAL RESISTANCE RATINGS			
Parameter	Symbol	Limit	Unit
Junction-to-Ambient (PCB Mount) ^c	R _{thJA}	60	°C/W
Junction-to-Case (Drain)	R _{thJC}	3	C/VV

Notes:

- a. Duty cycle \leq 1 %.
- b. See SOA curve for voltage derating.c. When mounted on 1" square PCB (FR-4 material).

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{DS} = 0 \text{ V}, I_{D} = -250 \mu\text{A}$	- 60			V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1		- 2.5	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 250	nA	
		V _{DS} = - 60 V, V _{GS} = 0 V			- 1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = - 60 V, V _{GS} = 0 V, T _J = 125 °C			- 50	μΑ	
		V _{DS} = - 60 V, V _{GS} = 0 V, T _J = 150 °C			- 250	1	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \le -10 \text{ V}, V_{GS} = -10 \text{ V}$	- 30			Α	
	D	V _{GS} = - 10 V, I _D = - 14 A		0.050		Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 12 A		0.060			
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 20 V, I _D = - 14 A		40		S	
Dynamic ^b							
Input Capacitance	C _{iss}			1765		pF	
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = -20 \text{ V}, f = 1 \text{ MHz}$		230			
Reverse Transfer Capacitance	C _{rss}			180			
Total Gate Charge ^c	Q_g			67			
Gate-Source Charge ^c	Q_{gs}	V _{DS} = - 20 V, V _{GS} = - 10 V, I _D = - 14 A		13.5		nC	
Gate-Drain Charge ^c	Q_{gd}			14		1	
Gate Resistance	R _g	f = 1 MHz	0.5	2.5	5	Ω	
Turn-On Delay Time ^c	t _{d(on)}			10	20		
Rise Time ^c	t _r	$V_{DD} = -20 \text{ V, R}_{L} = 2 \Omega$		11	20	- ns	
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong$ - 10 A, V_{GEN} = - 10 V, R_g = 1 Ω		42	63		
Fall Time ^c	t _f			12	20		
Drain-Source Body Diode Ratings ar	nd Characteri	stics T _C = 25 °C ^b					
Continuous Current	Is				- 36	^	
Pulsed Current	I _{SM}				- 100	Α	
Forward Voltage ^a	V _{SD}	I _F = - 10 A, V _{GS} = 0 V		- 0.8	- 1.5	V	
Reverse Recovery Time	t _{rr}			38	57	ns	
Peak Reverse Recovery Current	I _{RM(REC)}	I _F = - 10 A, dI/dt = 100 A/μs		2.3	3.5	Α	
Reverse Recovery Charge	Q _{rr}	1		40	60	nC	

Notes:

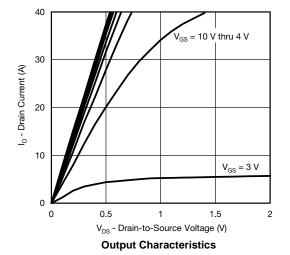
- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$ b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

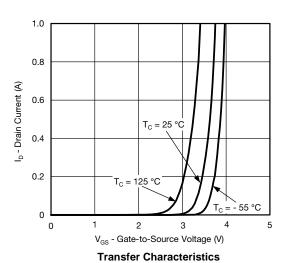
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

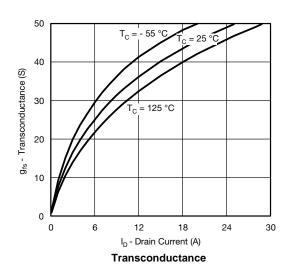
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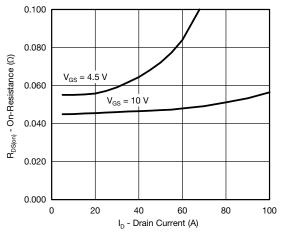


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

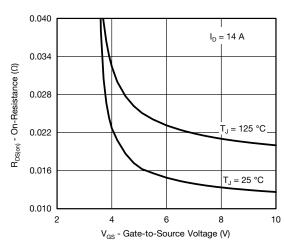




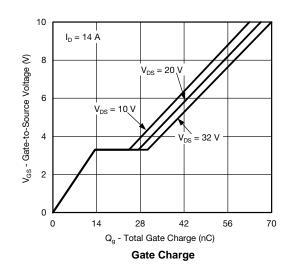




On-Resistance vs. Drain Current



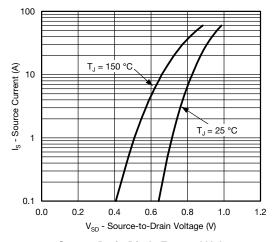
On-Resistance vs. Gate-to-Source Voltage



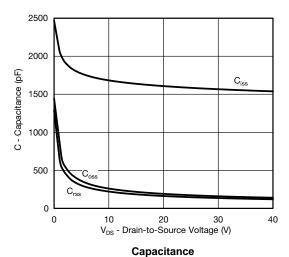
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

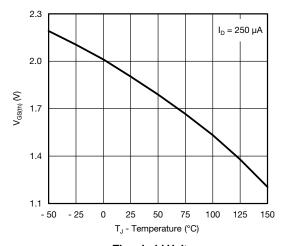


Source-Drain Diode Forward Voltage

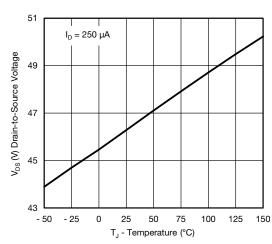


2.2 $I_D = 14 \text{ A}$ $V_{GS} = 10 \text{ V}$ $V_{GS} = 10 \text{ V}$ $V_{GS} = 4.5 \text{ V}$ $V_{GS} =$

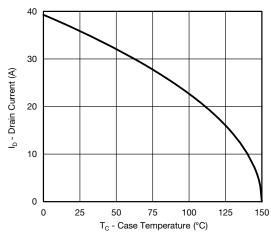
On-Resistance vs. Junction Temperature



Threshold Voltage



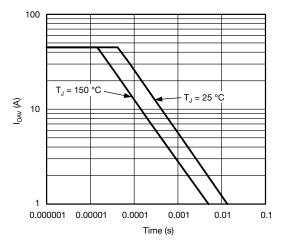
Drain Source Breakdown vs. Junction Temperature

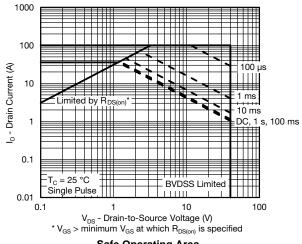


Current Derating



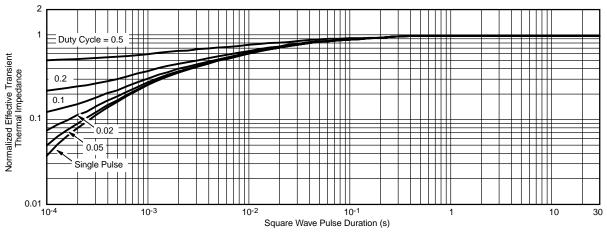
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)





Single Pulse Avalanche Current Capability vs. Time





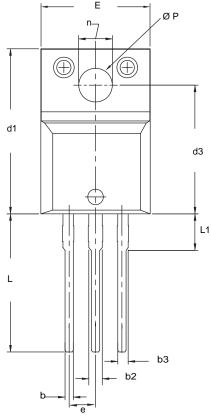
Normalized Thermal Transient Impedance, Junction-to-Case

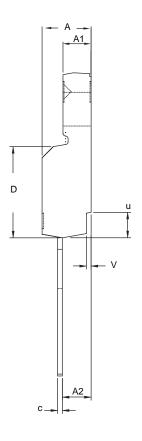
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TO-220 FULLPAK (HIGH VOLTAGE)





DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
А	4.570	4.830	0.180	0.190
A1	2.570	2.830	0.101	0.111
A2	2.510	2.850	0.099	0.112
b	0.622	0.890	0.024	0.035
b2	1.229	1.400	0.048	0.055
b3	1.229	1.400	0.048	0.055
С	0.440	0.629	0.017	0.025
D	8.650	9.800	0.341	0.386
d1	15.88	16.120	0.622	0.635
d3	12.300	12.920	0.484	0.509
E	10.360	10.630	0.408	0.419
е	2.54	BSC	0.100 BSC	
L	13.200	13.730	0.520	0.541
L1	3.100	3.500	0.122	0.138
n	6.050	6.150	0.238	0.242
ØΡ	3.050	3.450	0.120	0.136
u	2.400	2.500	0.094	0.098
V	0.400	0.500	0.016	0.020

ECN: X09-0126-Rev. B, 26-Oct-09 DWG: 5972

- To be used only for process drawing.
 These dimensions apply to all TO-220, FULLPAK leadframe versions 3 leads.
 All critical dimensions should C meet C_{pk} > 1.33.
 All dimensions include burrs and plating thickness.
 No chipping or package damage.

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